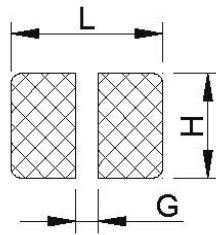


SPECIFICATION FOR APPROVAL

PAD LAYOUT: (UNIT: mm)



ITEM	L (Ref.)	G (Ref.)	H (Ref.)
FPI0302	4.5	1.1	3.3
FPI0311	4.5	1.1	3.3
FPI0315	4.5	1.1	3.3
FPI0402	5.5	1.5	4.5
FPI0403	5.5	1.5	4.5
FPI0519	6.5	1.7	5.5
FPI0502	6.5	1.7	5.5
FPI0503	6.5	1.7	5.5
FPI0504	6.5	1.7	5.5
FPI0703	8.5	2.0	7.5
FPI0705	8.5	2.0	7.5
FPI0706	8.5	2.0	7.5
FPI0707	8.5	2.0	7.5
FPI1004	12.5	2.5	9.5
FPI1005	12.5	2.5	9.5
FPI1006	12.5	2.5	9.5
FPI1008	12.5	2.5	9.5
FPI1206	14.0	4.5	14.0

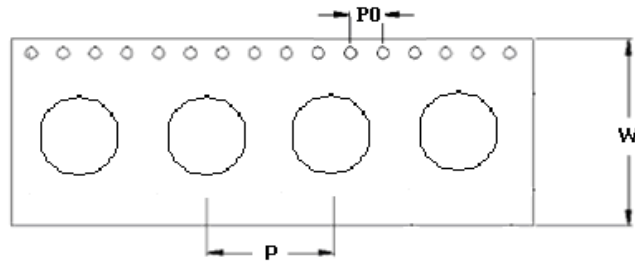


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SPECIFICATION FOR APPROVAL

PACKAGING QUANTITY: (UNIT: mm)



TYPE	P	P0	W	BULK	PCS / REEL
FPI0302	8.0 ± 0.1	4.0 ± 0.1	12.0 ± 0.3	v	3000
FPI0311	8.0 ± 0.1	4.0 ± 0.1	12.0 ± 0.3	v	3000
FPI0315	8.0 ± 0.1	4.0 ± 0.1	12.0 ± 0.3	v	3000
FPI0402	8.0 ± 0.1	4.0 ± 0.1	12.0 ± 0.3	v	2000
FPI0403	8.0 ± 0.1	4.0 ± 0.1	12.0 ± 0.3	v	2000
FPI0519	8.0 ± 0.1	4.0 ± 0.1	12.0 ± 0.3	v	2000
FPI0502	8.0 ± 0.1	4.0 ± 0.1	12.0 ± 0.3	v	2000
FPI0503	8.0 ± 0.1	4.0 ± 0.1	12.0 ± 0.3	v	2000
FPI0504	8.0 ± 0.1	4.0 ± 0.1	12.0 ± 0.3	v	1500
FPI0703	12.0 ± 0.1	4.0 ± 0.1	16.0 ± 0.3	v	1000
FPI0705	12.0 ± 0.1	4.0 ± 0.1	16.0 ± 0.3	v	1000
FPI0706	12.0 ± 0.1	4.0 ± 0.1	16.0 ± 0.3	v	700
FPI0707	12.0 ± 0.1	4.0 ± 0.1	16.0 ± 0.3	v	700
FPI1004	16.0 ± 0.1	4.0 ± 0.1	24.0 ± 0.3	v	1000
FPI1005	12.0 ± 0.1	4.0 ± 0.1	24.0 ± 0.3	v	500
FPI1006	16.0 ± 0.1	4.0 ± 0.1	24.0 ± 0.3	v	500
FPI1008	16.0 ± 0.1	4.0 ± 0.1	24.0 ± 0.3	v	400
FPI1206	16.0 ± 0.1	4.0 ± 0.1	24.0 ± 0.3	v	400

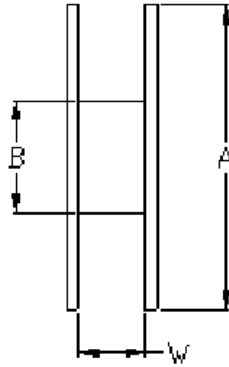
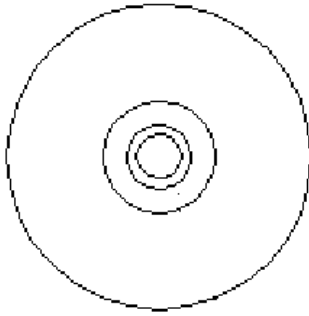


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SPECIFICATION FOR APPROVAL

PACKAGING QUANTITY: (UNIT: mm)



TYPE	A	B	W
FPI 0302	330	100	12.5
FPI 0311	330	100	12.5
FPI 0315	330	100	12.5
FPI 0402	330	100	12.5
FPI 0403	330	100	12.5
FPI 0519	330	100	12.5
FPI 0502	330	100	12.5
FPI 0503	330	100	12.5
FPI 0504	330	100	12.5
FPI 0703	330	100	16.5
FPI 0705	330	100	16.5
FPI 0706	330	100	16.5
FPI 0707	330	100	16.5
FPI 1004	330	100	24.5
FPI 1005	330	100	24.5
FPI 1006	330	100	24.5
FPI 1008	330	100	24.5
FPI 1206	330	100	24.5

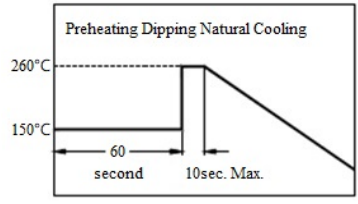


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SPECIFICATION FOR APPROVAL

RELIABILITY AND TEST CONDITIONS:

Item	Performance	Test Condition															
Operating Temperature	-40~+125℃																
Rated Current	Refer to standard electrical characteristics list.																
Temperature Rise Test	40℃ max. (Δt)																
Solder heat Resistance	Appearance: No significant abnormality. Inductance change: Within $\pm 30\%$.	Preheat:150℃,60sec. Solder : H63A Solder temperature:260+0-5℃ Flux: rosin Dip time:10sec. Max. 															
Thermal shock		Condition for 1 cycle Step1:-25±2℃ 30±3 min. Step2:Room temperature 15 min. Step3:+85±5℃ 30±3 min. Step4:Room temperature 15 min. Number of cycles:50 <table border="1"> <thead> <tr> <th>Phase</th><th>Temperature(℃)</th><th>Time(min)</th></tr> </thead> <tbody> <tr> <td>1</td><td>-25±2℃</td><td>30±3</td></tr> <tr> <td>2</td><td>Room Temp.</td><td>15</td></tr> <tr> <td>3</td><td>+85±2℃</td><td>30±3</td></tr> <tr> <td>4</td><td>Room Temp.</td><td>15</td></tr> </tbody> </table>	Phase	Temperature(℃)	Time(min)	1	-25±2℃	30±3	2	Room Temp.	15	3	+85±2℃	30±3	4	Room Temp.	15
Phase	Temperature(℃)	Time(min)															
1	-25±2℃	30±3															
2	Room Temp.	15															
3	+85±2℃	30±3															
4	Room Temp.	15															
Humidity Resistance Test	Appearance: no damage Inductance: within±30%of initial value.	Measured:50 times Temperature:40±2℃. Applied current: rated current. Duration:500 hrs. Humidity:90~95%															
High Temperature Resistance Test		Temperature:85±2℃. Applied current: rated current. Duration:500 hrs.															



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